

## N-Channel 60 V (D-S) MOSFET

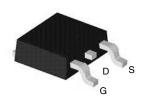
PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>			
60	0.0038 at V <sub>GS</sub> = 10 V	65			
00	0.0057 at V <sub>GS</sub> = 4.5 V	55			

#### **FEATURES**

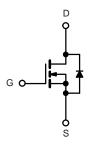
- 175 °C Junction Temperature
- DT-Trench Power MOSFET
- Material categorization:



#### TO-252 Pin Configuration



Top View



N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)					
Parameter		Symbol	Limit	Unit	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current /T 175 9C\D	T <sub>C</sub> = 25 °C	I-	65		
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 100 °C	I <sub>D</sub>	55 <sup>a</sup>		
Pulsed Drain Current	I <sub>DM</sub>	195	A		
Continuous Source Current (Diode Conduction)	I <sub>S</sub>	65 <sup>a</sup>			
Avalanche Current	I <sub>AS</sub>	60	7		
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E <sub>AS</sub>	155	mJ	
Maximum Dawar Dissination	T <sub>C</sub> = 25 °C	В	159	W	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	4 <sup>b</sup> , 8.9 <sup>b, c</sup>	T VV	
Operating Junction and Storage Temperature Range	<u>.</u>	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Marian and Innation to Ambient	t ≤ 10 sec	R <sub>thJA</sub>	12	18	°C/W	
Maximum Junction-to-Ambient <sup>a</sup>	Steady State		35	50		
Maximum Junction-to-Case		R <sub>thJC</sub>	0.84	1.1		

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- $c.\ t \leq 10\ s.$





<b>SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions Min.		Typ. <sup>a</sup>	Max.	Unit	
Static			L		l l		
Drain-Source Breakdown Voltage	ce Breakdown Voltage $V_{DS}$ $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ 60		60			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$ 1		2	3		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V			1	μA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C		50		
		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	50			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A		0.0038	0.0045		
5 1 6 6 6 6 6 6 6 6 6 6 6 6 6 6 6 6 6 6	D D	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A, T <sub>J</sub> = 125 °C		0.0040	0.0049		
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A, T <sub>J</sub> = 175 °C		0.0042	0.0051	Ω	
		$V_{GS} = 4.5 \text{ V}, I_D = 5 \text{ A}$		0.0057	0.0069		
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A		60		S	
Dynamic							
Input Capacitance	C <sub>iss</sub>			10950			
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		3570		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			225			
Total Gate Charge <sup>c</sup>	Qg			47	70		
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		10		nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			12			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			10	20		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 30 V, $R_L$ = 0.6 $\Omega$		15	25	no	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D\cong 50$ A, $V_{GEN}$ = 10 V, $R_g$ = 2.5 $\Omega$		35	50	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			20	30		
Source-Drain Diode Ratings and Cha	aracteristics (	T <sub>C</sub> = 25 °C)					
Pulsed Current	I <sub>SM</sub>				195	Α	
Diode Forward Voltage	$V_{SD}$	$I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$		1	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$		45	100	ns	

#### Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





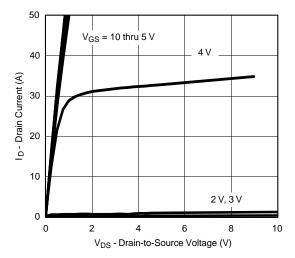
13000

0

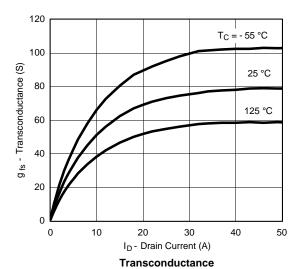
0

10

#### TYPICAL CHARACTERISTICS (25 °C unless noted)



#### **Output Characteristics**



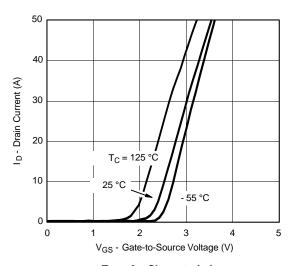
11500  $C_{\text{iss}}$ 9000 C - Capacitance (pF) 7500 6000 4500 3000 1500

V<sub>DS</sub> - Drain-to-Source Voltage (V) Capacitance

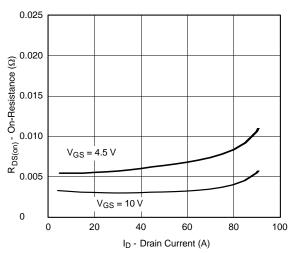
30

40

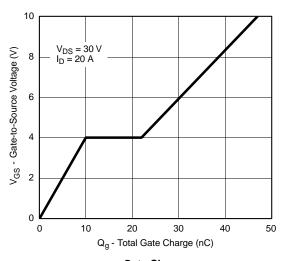
60



**Transfer Characteristics** 



**On-Resistance vs. Drain Current** 

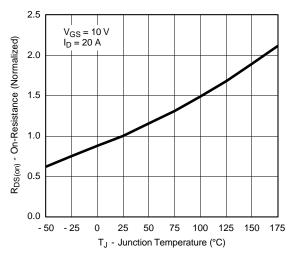


**Gate Charge** 

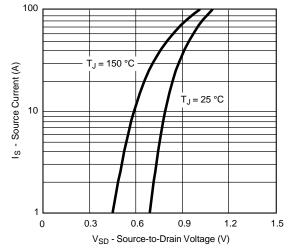




#### TYPICAL CHARACTERISTICS (25 °C unless noted)



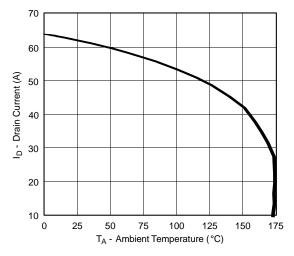
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage

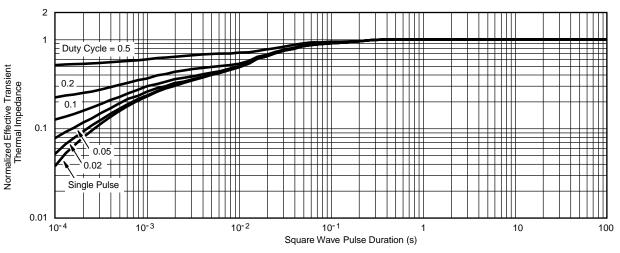


#### **THERMAL RATINGS**



Limited by  $R_{DS(on)^*}$  100  $\mu$  100

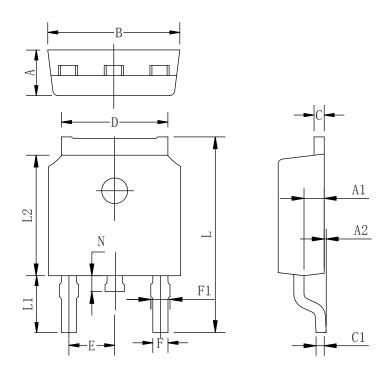
Maximum Drain Current vs. Ambient Temperature



Normalized Thermal Transient Impedance, Junction-to-Case



## TO-252-2L PACKAGE OUTLINE



# COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

Symbol	Min	Тур	Max		
A	2.10	2.30	2.50		
A1	0.88	1.01	1.16		
A2	0.00	0.15	0.28		
В	6.40	6.60	6.80		
С	0.42	0.50	0.63		
C1	0.42	0.50	0.63		
D	5.08	5.32	5.65		
Е	2.286 TYP				
F	0.63	0.76	0.89		
F1	0.64	0.86	1.08		
L	9.30	9.90	10.80		
L1	2.4	2.8	3.6		
L2	5.90	6.10	6.55		
N	0.57	0.80	1.05		





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